

POROUS ADHESIVE SHEET, SEMICONDUCTOR WAFER WITH POROUS ADHESIVE SHEET, AND METHOD OF MANUFACTURE THEREOF**Publication number:** WO0151580**Publication date:** 2001-07-19**Inventor:** YAMAGUCHI MIHO (JP); HOTTA YUJI (JP)**Applicant:** NITTO DENKO CORP (JP); YAMAGUCHI MIHO (JP); HOTTA YUJI (JP)**Classification:**

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A porous adhesive sheet (1) comprises adhesive organic film (3), in which a plurality of parallel through holes extend along the film thickness (A) between opposite ends (2a, 2b). The through holes have similar cross sections. A semiconductor wafer (31) provided with a porous adhesive sheet is manufactured using a semiconductor wafer (32) to which a porous adhesive sheet (1) is attached such that through holes (2) aligned with electrodes (33) on the wafer are filled with conductive material to form conductors (34).

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